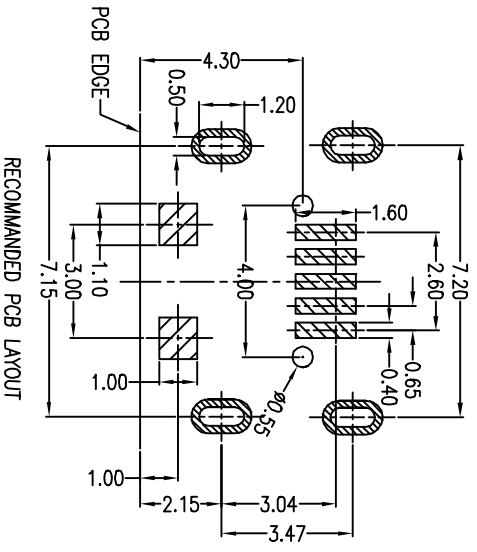
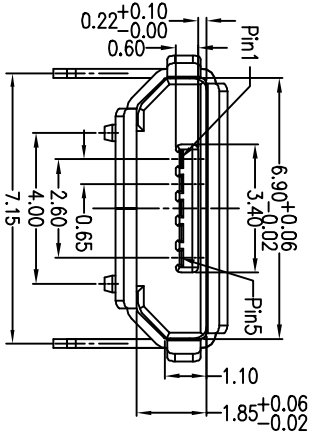
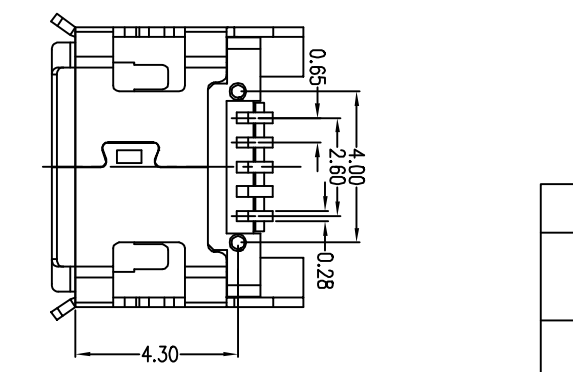
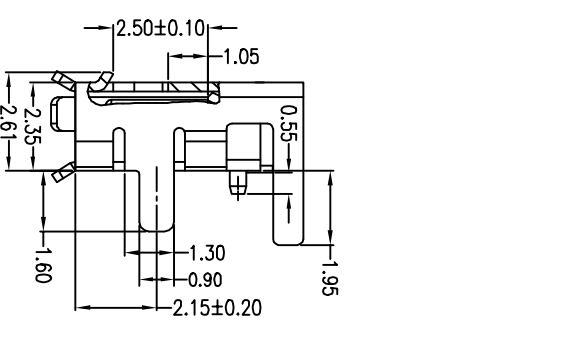
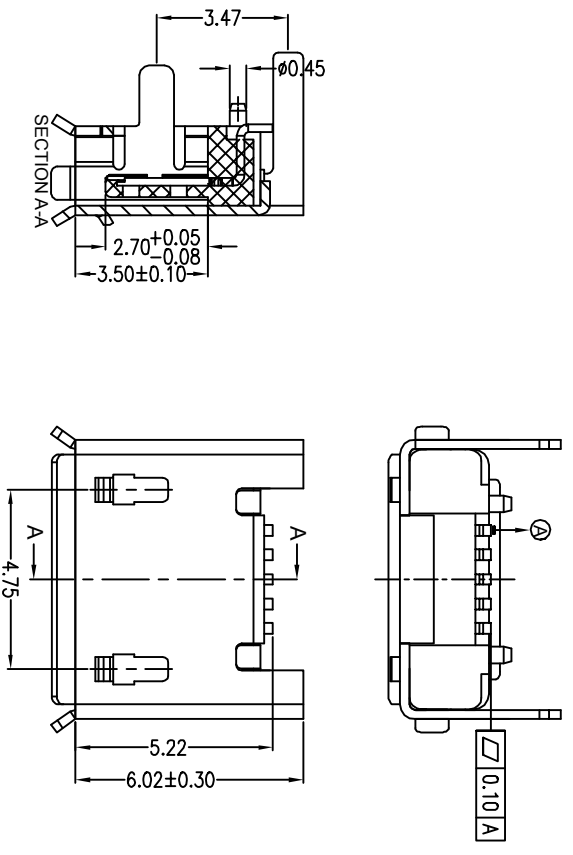


REV.	ECN NO	LOCATIONS	DESCRIPTION	DATE



RECOMMENDED PCB LAYOUT
PCB图仅供参考

- Note:
1. Material:
1.1 Housing: High temperature thermoplastic with g.f, UL 94V-0
1.2 Contact: copper alloy, t=0.20mm
1.3 Shell: copper alloy, t=0.25mm
2. Specification:
2.1 Current rating: 1.5PIN 1.8A Max/2,3,4PIN 1A Max voltage: 100 V(ac) for 1 min.
2.2 Dielectric withstanding
2.3 Contact resistance: 30 mΩ Max.
2.4 Insulation resistance: 100 MΩ Min.
2.5 Total mating force: 3.57 Kgf Max.
2.6 Total unmating force: 1.0 Kgf Min.
2.7 Temperature range: -30°C~80°C

- A 01 S B X X X X X X X X XX-520**
- ① 外壳材质
②
③
④
⑤
⑥
⑦
⑧
⑨
⑩
⑪
- 外壳电镀
1: COBROH-H
1: Ni100u''
2: 雾1100u''
3: Ni100u'' (脚)
4: Au1u''
- 端子电镀
01: Au1u'' ; 02: Au1.5u'' ; 03: Au60u''
05: Au50u'' ; 10: Au100u'' ; 15: Au150u'' ; 30: Au300u''
- 主体颜色 B: 黑色
主体材质 1: LCP
端子材质 4: QS191R-EH

PART NO:	A01SBXXXXXXX-520			MATERIAL:	SEE NOTE
MODEL NO:	XX			FINSH:	SEE NOTE
UNIT:	MM	SIZE:	A4	COLOR:	SEE NOTE
TOLERANCE UNSPECIFIED					
	.x	0.15		DR:	xiaoyulong
	.xx	0.10		CHK:	
	.xxx	0.05		APP:	
	Ang.	1°			

深圳扬讯电子有限公司

TITLE: Micro usb sp B Type 插板 2 在 柱前脚1, 6后脚1, 95四脚插
加长0.2

DWG NO: AS20

SCALE: 5:1

DATE: 2015.03.19

REV: A